|                           | Material Composition Declaration<br>© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under<br>international and Pan-American copyright conventions. |                           |                                  | nder both       | This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assen<br>level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering resp |                            |                     |                             |        |                                 |                         |                  | sembly with lowe<br>responsibility. |      |           |
|---------------------------|--|---------------------------|----------------------------------|-----------------|---|----------------------------|---------------------|-----------------------------|--------|---------------------------------|-------------------------|------------------|-------------------------------------|------|-----------|
| 1752-21.1                 | IPC Web Site for Information on IPC-1752 Standard Form Type<br>http://www.ipc.org/IPC-175x Distribute  |                           |                                  |                 | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materi  |                            |                     |                             |        | ous Materia                     | als and Mfg Information |                  |                                     |      |           |
| Supplier                  | r Information  |                           |                                  |                 |   |                            |                     |                             |        |                                 |                         |                  |                                     |      |           |
| Company name* Compan      |  |                           |                                  | npany unique ID |   |                            | Unique ID Authority |                             |        |                                 |                         | Response Date*   |                                     |      |           |
| onsemi                    |  |                           |                                  |                 |   |                            |                     |                             |        |                                 |                         | 2025-07-05       |                                     |      |           |
| Contact N                 | lame   | Title - Contact           |                                  |                 |   | Phone - Contact*           |                     |                             |        | Email - Contact*                |                         |                  |                                     |      |           |
| Product-I                 | Env-Stewards   | Product Enviro Compliance |                                  |                 |   | NA                         |                     |                             |        | Product-Env-Stewards@onsemi.com |                         |                  |                                     |      |           |
| uthorize                  | ed Representative*   | Title - Representative    |                                  |                 |   | Phone - Representative*    |                     |                             |        | Email - Representative*         |                         |                  |                                     |      |           |
| Product-I                 | Env-Stewards   | Product Enviro Compliance |                                  |                 |   | NA                         |                     |                             |        | Product-Env-Stewards@onsemi.com |                         |                  |                                     |      |           |
|                           | Requester Item Number Mfr Item   |                           | Number Mfr Item Name             |                 |   |                            | Effective Date      | e Vei                       | rsion  | sion Manufacturing Site         |                         | v                | Veight*                             | UOM  | Unit Type |
|                           |  | MBR360G REC SURM 3A 60    |                                  |                 | 50V SHTKY   |                            | 2025-07-05          | 15 CNP                      |        |                                 | 1                       | 334.62           | mg                                  | Each |           |
| /Ianufa                   | cturing Proccess Information   | tion                      |                                  |                 |   |                            |                     |                             |        |                                 |                         |                  |                                     |      |           |
|                           | Terminal Plating / Grid Array Material   |                           | Cerminal Base Alloy J-STD-020 MS |                 | L Rating  | Peak Process Body Temperat |                     | ure Max Time at Peak Temper |        | Temperatu                       | ire Numb                | er of Reflow Cyc | eles                                |      |           |
| Matte Tin (Sn) - annealed |  | CU Alloy NA               |                                  |                 | 0 C   |                            | 30 seco             |                             | second | is 3                            |                         |                  |                                     |      |           |
| omments                   | 3  |                           |                                  |                 |   |                            |                     |                             |        |                                 |                         |                  |                                     |      |           |
|                           |  |                           |                                  |                 |   |                            |                     |                             |        |                                 |                         |                  |                                     |      |           |
| or more i                 | information regarding material   | composition               | please refer to                  | page 3          |   |                            |                     |                             |        |                                 |                         |                  |                                     |      |           |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *  | Detailed  |  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | amending RoHS RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>iffies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the  | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst   | ances per the definition above except for sele   | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol   | der alloys containing 85% by weight or m   | ore lead).  |   |   |  |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |   |  | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |  |  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska  | Le   |   |   |   |  |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

|                      | cable [E] enter the weigh |                 |          | Ince category (JIG or Requester) or enter<br>[F] Optionally enter the positive (+) and |                  |        |          |                 |
|----------------------|---------------------------|-----------------|----------|--|------------------|--------|----------|-----------------|
| Homogeneous Material | Weight                    | Unit of Measure | Level    | Substance  | CAS              | Exempt | Weight   | Unit of Measure |
| Die                  | 6.67                      | mg              | Supplier | Silicon (Si)   | 7440-21-3        |        | 6.67     | mg              |
| Die Attach Solder    | 46.69                     | mg              | Supplier | Silver (Ag)  | 7440-22-4        |        | 1.1673   | mg              |
|                      |                           |                 | А        | Lead (Pb)  | 7439-92-1        | 7a     | 43.1882  | mg              |
|                      |                           |                 | Supplier | Tin (Sn)   | 7440-31-5        |        | 2.3345   | mg              |
| Lead Frame           | 731.48                    | mg              | Supplier | Copper (Cu)  | 7440-50-8        |        | 731.48   | mg              |
| Mold Compound-Black  | 543.33                    | mg              |          | Epoxy resin  | proprietary data |        | 38.0331  | mg              |
|                      |                           |                 | Supplier | Phenolic Resin   | Proprietary Data |        | 38.0331  | mg              |
|                      |                           |                 | Supplier | Silica Amorphous (SiO2)  | 7631-86-9        |        | 81.4995  | mg              |
|                      |                           |                 | Supplier | Carbon Black (C)   | 1333-86-4        |        | 2.7167   | mg              |
|                      |                           |                 | Supplier | Fused Silica (SiO2)  | 60676-86-0       |        | 383.0476 | mg              |
| Plating              | 6.45                      | mg              | Supplier | Tin (Sn)   | 7440-31-5        |        | 6.45     | mg              |